

# FDB2710

## N-Channel PowerTrench® MOSFET

250 V, 50 A, 42.5 mΩ

### Features

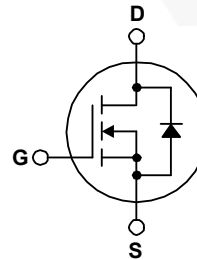
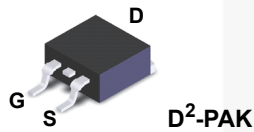
- $R_{DS(on)} = 36.3 \text{ m}\Omega$  (Typ.)@  $V_{GS} = 10 \text{ V}$ ,  $I_D = 25 \text{ A}$
- High Performance Trench Technology for Extremely Low  $R_{DS(on)}$
- Low Gate Charge
- High Power and Current Handling Capability

### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

### Applications

- Synchronous Rectification
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FDB2710	Unit
$V_{DS}$	Drain-Source Voltage	250	V
$V_{GS}$	Gate-Source voltage	$\pm 30$	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ ) - Continuous ( $T_C = 100^\circ\text{C}$ )	50	A
		31.3	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	See Figure 9	A
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	145	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ ) - Derate above $25^\circ\text{C}$	260	W
		2.1	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FDB2710	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.48	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (minimum pad of 2 oz copper), Max.	62.5	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (1 in <sup>2</sup> pad of 2 oz copper), Max.	40	$^\circ\text{C}/\text{W}$

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB2710	FDB2710	D <sup>2</sup> -PAK	330 mm	24 mm	800 units

## Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 25°C	250	--	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C	--	0.25	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 250V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 250V, V <sub>GS</sub> = 0V, T <sub>C</sub> = 125°C	--	--	1 500	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	3.0	4.0	5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 25A	--	36.3	42.5	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10V, I <sub>D</sub> = 25A	--	63	--	S
<b>Dynamic Characteristics</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	--	5470	7280	pF
C <sub>OSS</sub>	Output Capacitance		--	426	570	pF
C <sub>RSS</sub>	Reverse Transfer Capacitance		--	97	146	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 125V, I <sub>D</sub> = 50A V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 25Ω  (Note 4)	--	80	170	ns
t <sub>r</sub>	Turn-On Rise Time		--	252	515	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	112	235	ns
t <sub>f</sub>	Turn-Off Fall Time		--	154	320	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 125V, I <sub>D</sub> = 50A V <sub>GS</sub> = 10V  (Note 4)	--	78	101	nC
Q <sub>gs</sub>	Gate-Source Charge		--	34	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	18	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	50	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	150	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 50A	--	--	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>S</sub> = 50A di <sub>F</sub> /dt = 100A/μs	--	163	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	1.3	--	μC

### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 1mH, I<sub>AS</sub> = 17A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C
3. I<sub>SD</sub> ≤ 50A, di/dt ≤ 100A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>. Starting T<sub>J</sub> = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

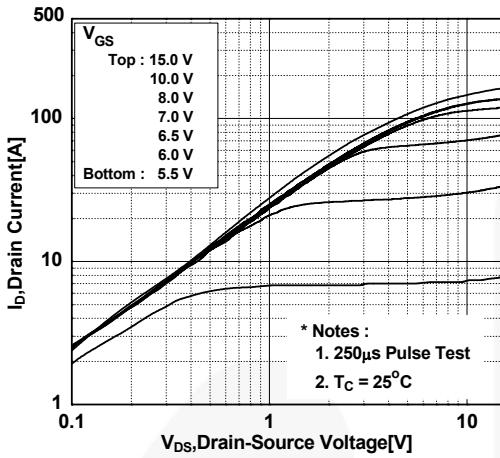


Figure 2. Transfer Characteristics

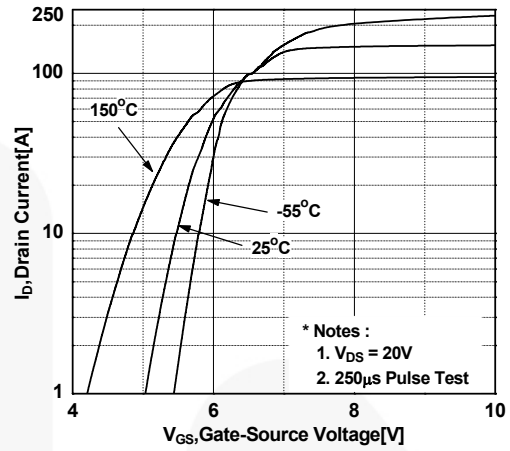


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

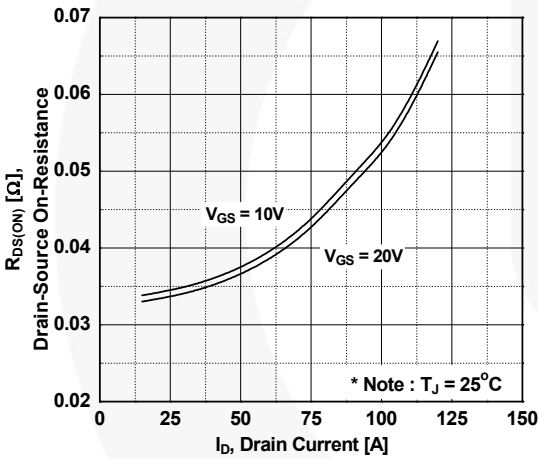


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

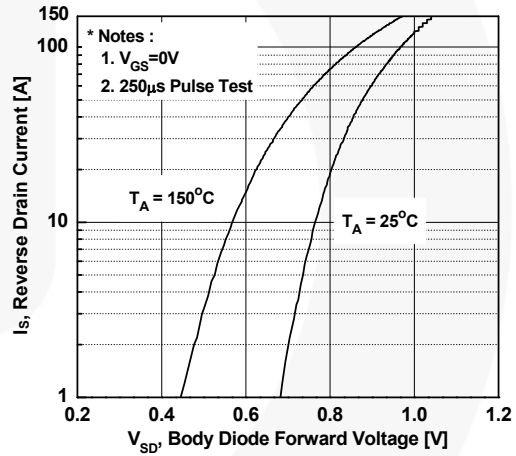


Figure 5. Capacitance Characteristics

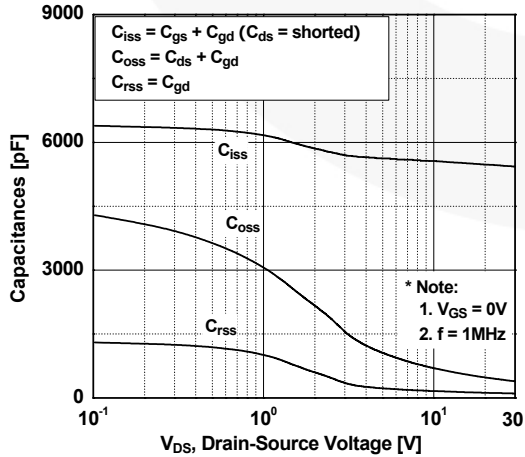
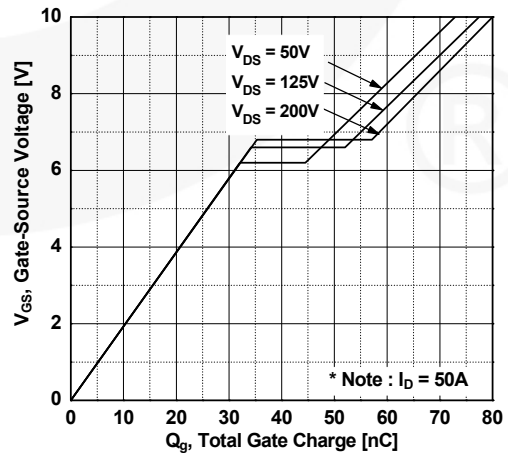


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

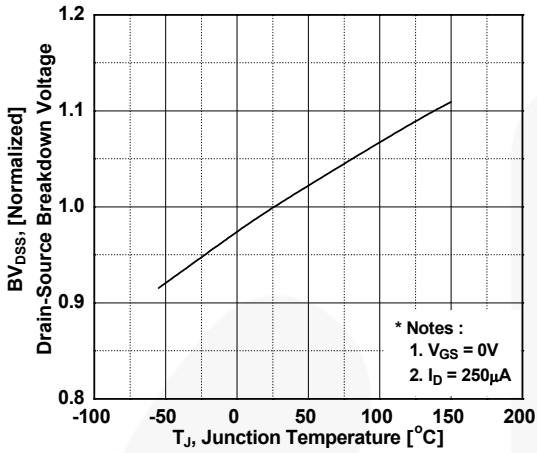


Figure 8. On-Resistance Variation vs. Temperature

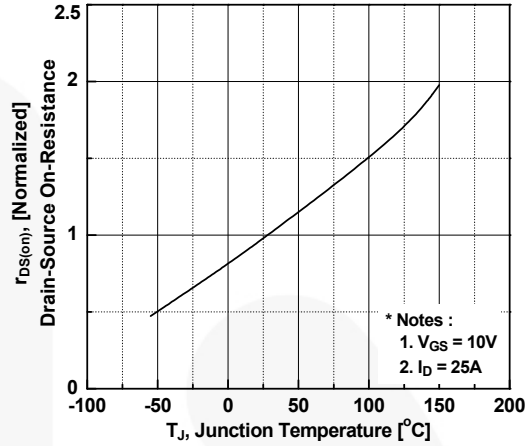


Figure 9. Maximum Safe Operating Area

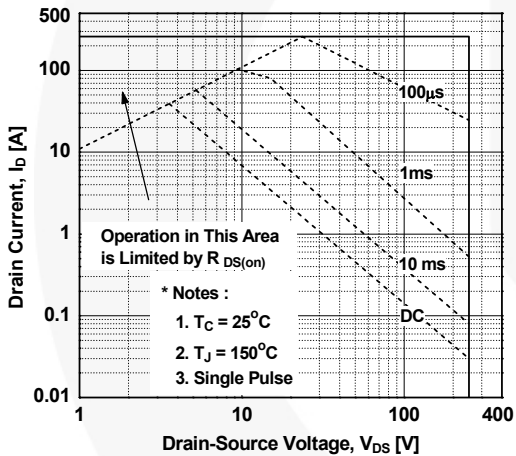


Figure 10. Maximum Drain Current vs. Case Temperature

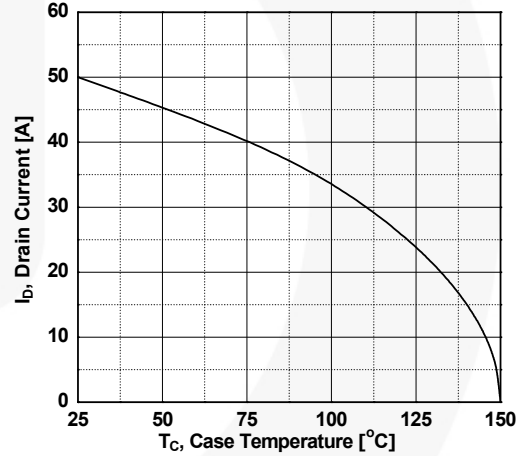
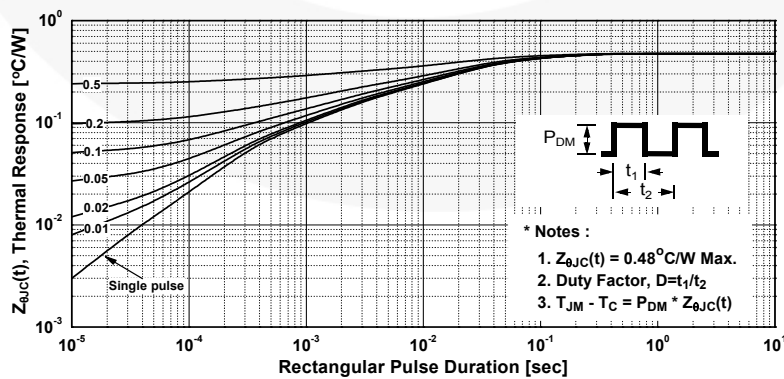
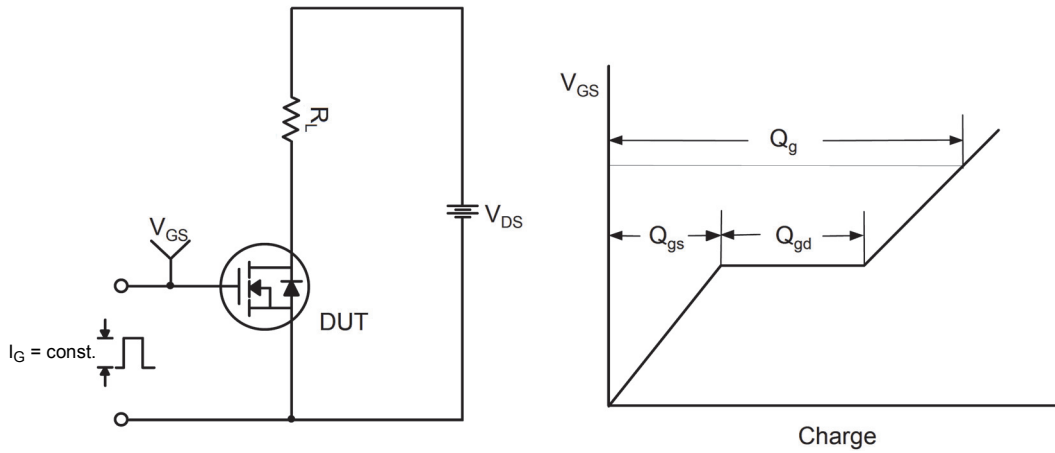


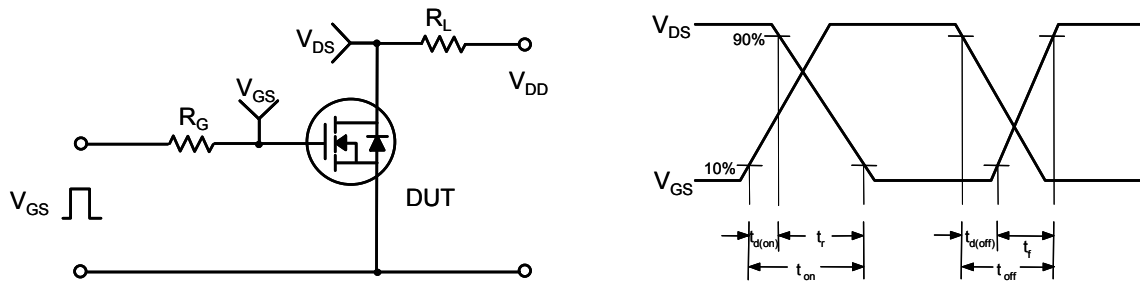
Figure 11. Transient Thermal Response Curve



**Figure 12. Gate Charge Test Circuit & Waveform**



**Figure 13. Resistive Switching Test Circuit & Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

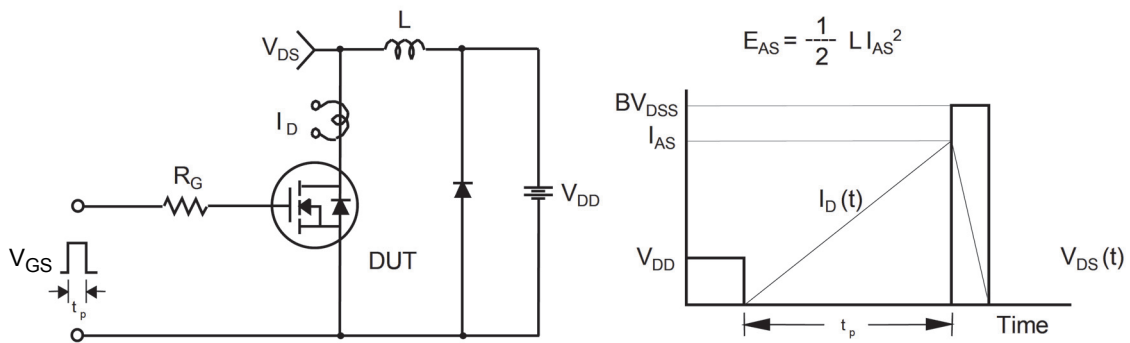
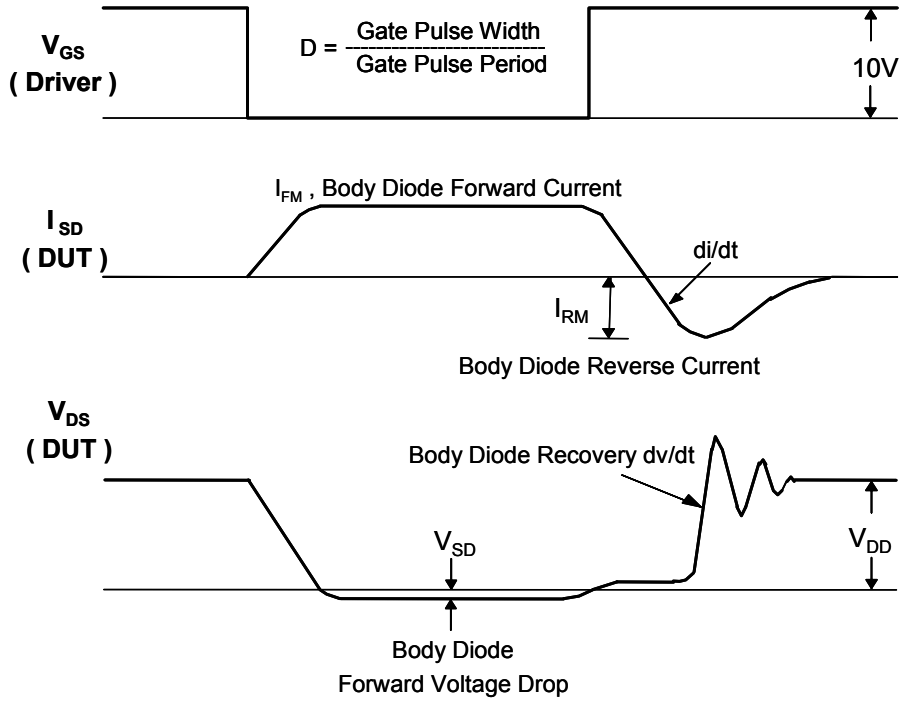
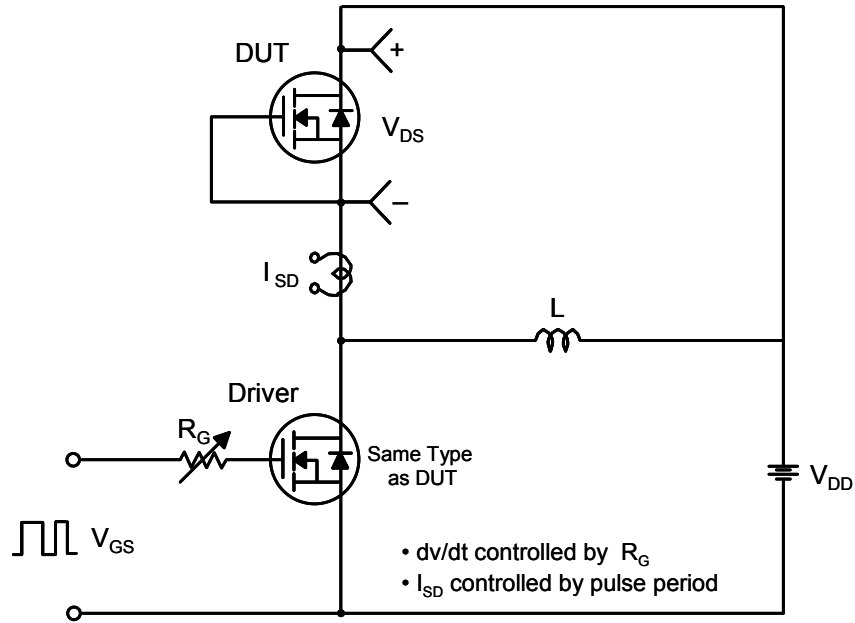
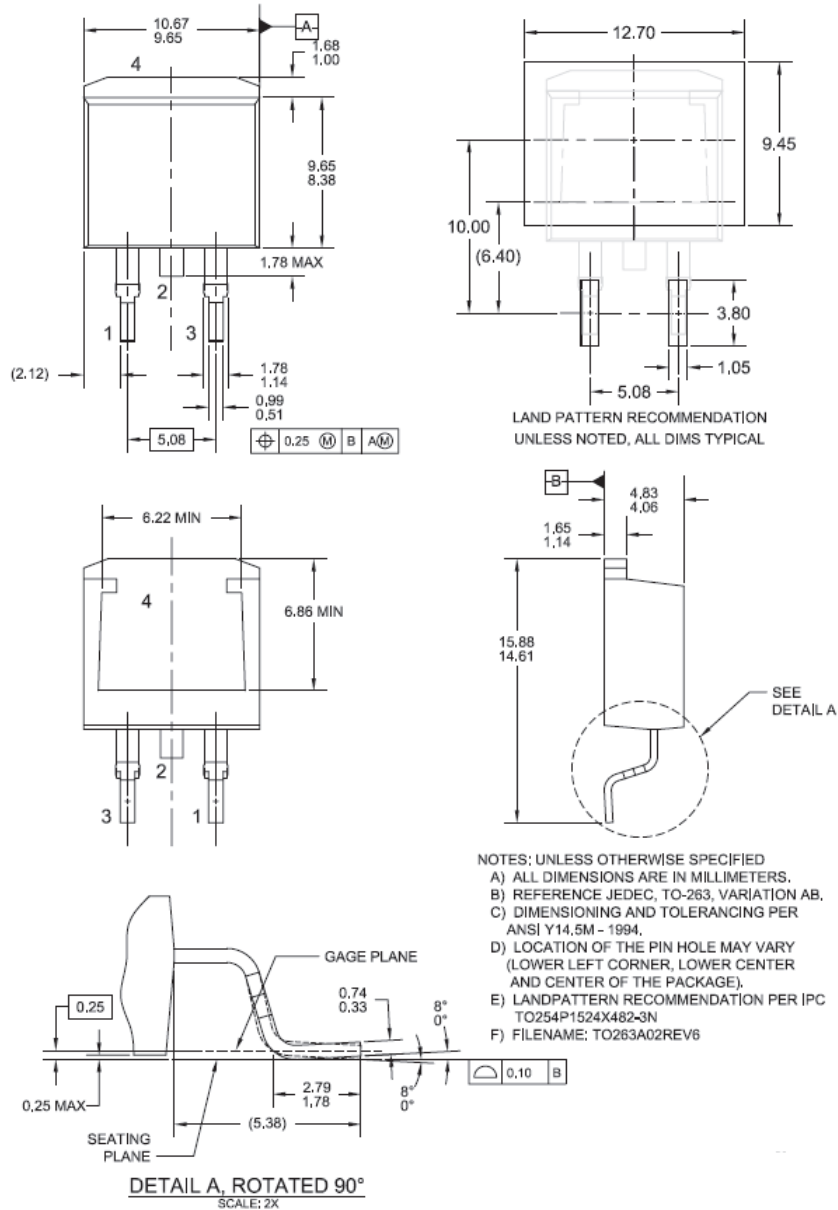


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



**Mechanical Dimensions**

**TO-263 2L (D<sup>2</sup>PAK)**



**Figure 16. 2LD, TO263, Surface Mount**

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Dimension in Millimeters



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| Build it Now™            | GreenBridge™            | QFET®   | TinyBuck®        |
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| FACT Quiet Series™       |                         | SuperFET®                                       | UniFET™          |
| FACT®                    |                         | SuperSOT™-3                                     | VCX™             |
| FAST®                    |                         | SuperSOT™-6                                     | VisualMax™       |
| FastvCore™               |                         | SuperSOT™-8                                     | VoltagePlus™     |
| FETBench™                |                         | SupreMOS®                                       | XS™              |
| FPS™                     |                         | SyncFET™  |                  |

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